

PATENT APPLICATION

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IN THE U.S. PATENT AND TRADEMARK OFFICE

April 14, 2006

Applicants : Atsushi YABE et al  
For : ELECTROLESS COPPER PLATING SOLUTION AND  
ELECTROLESS COPPER PLATING METHOD

PCT International Application No.: PCT/JP2004/014049

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U.S. Application No.

(if known, see 37 CFR 1.5): Unknown

Atty. Docket No.: 4700.P0328US

Mail Stop PCT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT BEFORE FIRST OFFICE ACTION**

Sir:

Prior to issuance of the first Office Action in the  
above-identified application, kindly enter the following:

(Please see following pages.)